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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	EBI/EMI, I ² C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	88
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-LQFP (20x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at91sam7se32b-aur

1. Description

Atmel's SAM7SE Series is a member of its Smart ARM Microcontroller family based on the 32-bit ARM7™ RISC processor and high-speed Flash memory.

- SAM7SE512 features a 512-Kbyte high-speed Flash and a 32 Kbyte SRAM.
- SAM7SE256 features a 256-Kbyte high-speed Flash and a 32 Kbyte SRAM.
- SAM7SE32 features a 32-Kbyte high-speed Flash and an 8 Kbyte SRAM.

It also embeds a large set of peripherals, including a USB 2.0 device, an External Bus Interface (EBI), and a complete set of system functions minimizing the number of external components.

The EBI incorporates controllers for synchronous DRAM (SDRAM) and Static memories and features specific circuitry facilitating the interface for NAND Flash, SmartMedia and CompactFlash.

The device is an ideal migration path for 8/16-bit microcontroller users looking for additional performance, extended memory and higher levels of system integration.

The embedded Flash memory can be programmed in-system via the JTAG-ICE interface or via a parallel interface on a production programmer prior to mounting. Built-in lock bits and a security bit protect the firmware from accidental overwrite and preserve its confidentiality.

The SAM7SE Series system controller includes a reset controller capable of managing the power-on sequence of the microcontroller and the complete system. Correct device operation can be monitored by a built-in brownout detector and a watchdog running off an integrated RC oscillator.

By combining the ARM7TDMI processor with on-chip Flash and SRAM, and a wide range of peripheral functions, including USART, SPI, External Bus Interface, Timer Counter, RTT and Analog-to-Digital Converters on a monolithic chip, the SAM7SE512/256/32 is a powerful device that provides a flexible, cost-effective solution to many embedded control applications.

1.1 Configuration Summary of the SAM7SE512, SAM7SE256 and SAM7SE32

The SAM7SE512, SAM7SE256 and SAM7SE32 differ in memory sizes and organization. [Table 1-1](#) below summarizes the configurations for the three devices.

Table 1-1. Configuration Summary

Device	Flash Size	Flash Organization	RAM Size
SAM7SE512	512K bytes	dual plane	32K bytes
SAM7SE256	256K bytes	single plane	32K bytes
SAM7SE32	32K bytes	single plane	8K bytes

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Comments
Two-Wire Interface				
TWD	Two-wire Serial Data	I/O		
TWCK	Two-wire Serial Clock	I/O		
Analog-to-Digital Converter				
AD0-AD3	Analog Inputs	Analog		Digital pulled-up inputs at reset
AD4-AD7	Analog Inputs	Analog		Analog Inputs
ADTRG	ADC Trigger	Input		
ADVREF	ADC Reference	Analog		
Fast Flash Programming Interface				
PGMEN0-PGMEN2	Programming Enabling	Input		
PGMM0-PGMM3	Programming Mode	Input		
PGMD0-PGMD15	Programming Data	I/O		
PGMRDY	Programming Ready	Output	High	
PGMNVALID	Data Direction	Output	Low	
PGMNOE	Programming Read	Input	Low	
PGMCK	Programming Clock	Input		
PGMNCMD	Programming Command	Input	Low	
External Bus Interface				
D[31:0]	Data Bus	I/O		
A[22:0]	Address Bus	Output		
NWAIT	External Wait Signal	Input	Low	
Static Memory Controller				
NCS[7:0]	Chip Select Lines	Output	Low	
NWR[1:0]	Write Signals	Output	Low	
NRD	Read Signal	Output	Low	
NWE	Write Enable	Output	Low	
NUB	NUB: Upper Byte Select	Output	Low	
NLB	NLB: Lower Byte Select	Output	Low	
EBI for CompactFlash Support				
CFCE[2:1]	CompactFlash Chip Enable	Output	Low	
CFOE	CompactFlash Output Enable	Output	Low	
CFWE	CompactFlash Write Enable	Output	Low	
CFIOR	CompactFlash I/O Read Signal	Output	Low	
CFIOW	CompactFlash I/O Write Signal	Output	Low	
CFRNW	CompactFlash Read Not Write Signal	Output		
CFCS[1:0]	CompactFlash Chip Select Lines	Output	Low	

Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Comments
EBI for NAND Flash Support				
NANDCS	NAND Flash Chip Select Line	Output	Low	
NANDOE	NAND Flash Output Enable	Output	Low	
NANDWE	NAND Flash Write Enable	Output	Low	
NANDCLE	NAND Flash Command Line Enable	Output	Low	
NANDALE	NAND Flash Address Line Enable	Output	Low	
SDRAM Controller				
SDCK	SDRAM Clock	Output		Tied low after reset
SDCKE	SDRAM Clock Enable	Output	High	
SDCS	SDRAM Controller Chip Select Line	Output	Low	
BA[1:0]	Bank Select	Output		
SDWE	SDRAM Write Enable	Output	Low	
RAS - CAS	Row and Column Signal	Output	Low	
NBS[3:0]	Byte Mask Signals	Output	Low	
SDA10	SDRAM Address 10 Line	Output		

Note: 1. Refer to [Section 6. "/O Lines Considerations" on page 15.](#)

6. /O Lines Considerations

6.1 JTAG Port Pins

TMS, TDI and TCK are Schmitt trigger inputs. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 k Ω .

To eliminate any risk of spuriously entering the JTAG boundary scan mode due to noise on JTAGSEL, it should be tied externally to GND if boundary scan is not used, or put in place an external low value resistor (such as 1 k Ω).

6.2 Test Pin

The TST pin is used for manufacturing test or fast programming mode of the SAM7SE512/256/32 when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 k Ω to GND.

To eliminate any risk of entering the test mode due to noise on the TST pin, it should be tied to GND if the FFPI is not used, or put in place an external low value resistor (such as 1 k Ω).

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied low.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

6.3 Reset Pin

The NRST pin is bidirectional with an open-drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the NRST pin as system user reset, and the use of the NRST signal to reset all the components of the system.

An external power-on reset can drive this pin during the start-up instead of using the internal power-on reset circuit.

The NRST pin integrates a permanent pull-up of about 100 k Ω resistor to VDDIO.

This pin has Schmitt trigger input.

6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 k Ω to GND.

To eliminate any risk of erasing the Flash due to noise on the ERASE pin, it should be tied externally to GND, which prevents erasing the Flash from the application, or put in place an external low value resistor (such as 1 k Ω).

This pin is debounced by the RC oscillator to improve the glitch tolerance. When the pin is tied to high during less than 100 ms, ERASE pin is not taken into account. The pin must be tied high during more than 220 ms to perform the re-initialization of the Flash.

6.5 SDCK Pin

The SDCK pin is dedicated to the SDRAM Clock and is an output-only without pull-up. Maximum Output Frequency of this pad is 48 MHz at 3.0V and 25 MHz at 1.65V with a maximum load of 30 pF.

6.6 PIO Controller lines

All the I/O lines PA0 to PA31, PB0 to PB31, PC0 to PC23 integrate a programmable pull-up resistor. Programming of this pull-up resistor is performed independently for each I/O line through the PIO controllers.

Typical pull-up value is 100 k Ω .

All the I/O lines have schmitt trigger inputs.

6.7 I/O Lines Current Drawing

The PIO lines PA0 to PA3 are high-drive current capable. Each of these I/O lines can drive up to 16 mA permanently.

The remaining I/O lines can draw only 8 mA.

However, the total current drawn by all the I/O lines cannot exceed 300 mA.

- Multiple device adaptability
 - Compliant with LCD Module
 - Compliant with PSRAM in synchronous operations
 - Programmable Setup Time Read/Write
 - Programmable Hold Time Read/Write
- Multiple Wait State Management
 - Programmable Wait State Generation
 - External Wait Request
 - Programmable Data Float Time

7.6 SDRAM Controller

- Numerous configurations supported
 - **2K, 4K, 8K Row Address Memory Parts**
 - **SDRAM with two or four Internal Banks**
 - **SDRAM with 16- or 32-bit Data Path**
- Programming facilities
 - **Word, half-word, byte access**
 - **Automatic page break when Memory Boundary has been reached**
 - **Multibank Ping-pong Access**
 - **Timing parameters specified by software**
 - **Automatic refresh operation, refresh rate is programmable**
- Energy-saving capabilities
 - **Self-refresh, and Low-power Modes supported**
- Error detection
 - **Refresh Error Interrupt**
- **SDRAM Power-up Initialization by software**
- **Latency is set to two clocks (CAS Latency of 1, 3 Not Supported)**
- **Auto Precharge Command not used**
- Mobile SDRAM supported (except for low-power extended mode and deep power-down mode)

7.7 Error Corrected Code Controller

- Tracking the accesses to a NAND Flash device by triggering on the corresponding chip select
- Single bit error correction and 2-bit Random detection.
- Automatic Hamming Code Calculation while writing
 - ECC value available in a register
- Automatic Hamming Code Calculation while reading
 - Error Report, including error flag, correctable error flag and word address being detected erroneous
 - Supports 8- or 16-bit NAND Flash devices with 512-, 1024-, 2048- or 4096-byte pages

Figure 8-2. Internal Memory Mapping with GPNVM Bit 2 = 0 (default)

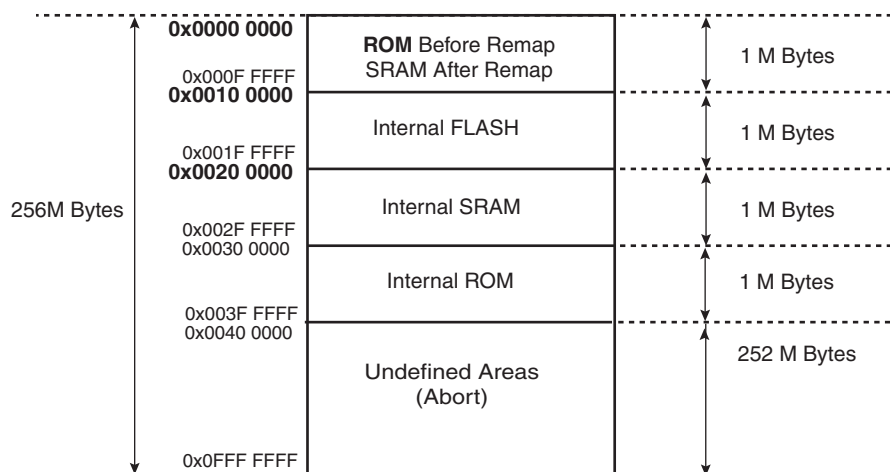
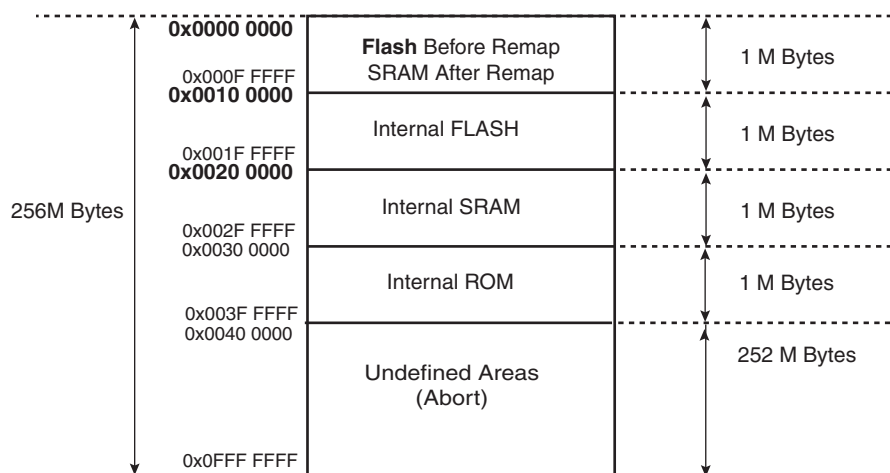


Figure 8-3. Internal Memory Mapping with GPNVM Bit 2 = 1



8.1.2 Embedded Flash

8.1.2.1 Flash Overview

The Flash of the SAM7SE512 is organized in two banks (dual plane) of 1024 pages of 256 bytes. It reads as 131,072 32-bit words.

The Flash of the SAM7SE256 is organized in 1024 pages (single plane) of 256 bytes. It reads as 65,536 32-bit words.

The Flash of the SAM7SE32 is organized in 256 pages (single plane) of 128 bytes. It reads as 8192 32-bit words.

The Flash of the SAM7SE32 contains a 128-byte write buffer, accessible through a 32-bit interface.

The Flash of the SAM7SE512/256 contains a 256-byte write buffer, accessible through a 32-bit interface.

The Flash benefits from the integration of a power reset cell and from the brownout detector. This prevents code corruption during power supply changes, even in the worst conditions.

8.1.2.2 *Embedded Flash Controller*

The Embedded Flash Controller (EFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped within the Memory Controller on the APB. The User Interface allows:

- programming of the access parameters of the Flash (number of wait states, timings, etc.)
- starting commands such as full erase, page erase, page program, NVM bit set, NVM bit clear, etc.
- getting the end status of the last command
- getting error status
- programming interrupts on the end of the last commands or on errors

The Embedded Flash Controller also provides a dual 32-bit Prefetch Buffer that optimizes 16-bit access to the Flash. This is particularly efficient when the processor is running in Thumb mode.

- Two EFCs (EFC0 and EFC1) are embedded in the SAM7SE512 to control each plane of 256 KBytes. Dual plane organization allows concurrent Read and Program.
- One EFC (EFC0) is embedded in the SAM7SE256 to control the single plane 256 KBytes.
- One EFC (EFC0) is embedded in the SAM7SE32 to control the single plane 32 KBytes.

8.1.2.3 *Lock Regions*

The SAM7SE512 Embedded Flash Controller manages 32 lock bits to protect 32 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE512 contains 32 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

The SAM7SE256 Embedded Flash Controller manages 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE256 contains 16 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

The SAM7SE32 Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7SE32 contains 8 lock regions and each lock region contains 32 pages of 128 bytes. Each lock region has a size of 4 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the EFC triggers an interrupt.

The 32 (SAM7SE512), 16 (SAM7SE256) or 8 (SAM7SE32) NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.1.2.4 *Security Bit Feature*

The SAM7SE512/256/32 features a security bit, based on a specific NVM-bit. When the security is enabled, any access to the Flash, either through the ICE interface or through the Fast Flash Programming Interface, is forbidden.

The security bit can only be enabled through the Command “Set Security Bit” of the EFC User Interface. Disabling the security bit can only be achieved by asserting the ERASE pin at 1 and after a full flash erase is performed. When the security bit is deactivated, all accesses to the flash are permitted.

It is important to note that the assertion of the ERASE pin should always be longer than 200 ms.

As the ERASE pin integrates a permanent pull-down, it can be left unconnected during normal operation. However, it is safer to connect it directly to GND for the final application.

8.1.2.5 *Non-volatile Brownout Detector Control*

Two general purpose NVM (GPNVM) bits are used for controlling the brownout detector (BOD), so that even after a power loss, the brownout detector operations remain in their state.

These two GPNVM bits can be cleared or set respectively through the commands “Clear General-purpose NVM Bit” and “Set General-purpose NVM Bit” of the EFC User Interface.

- GPNVM bit 0 is used as a brownout detector enable bit. Setting the GPNVM bit 0 enables the BOD, clearing it disables the BOD. Asserting ERASE clears the GPNVM bit 0 and thus disables the brownout detector by default.
- GPNVM bit 1 is used as a brownout reset enable signal for the reset controller. Setting the GPNVM bit 1 enables the brownout reset when a brownout is detected, Clearing the GPNVM bit 1 disables the brownout reset. Asserting ERASE disables the brownout reset by default.

8.1.2.6 *Calibration Bits*

Sixteen NVM bits are used to calibrate the brownout detector and the voltage regulator. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the calibration bits.

8.1.3 **Fast Flash Programming Interface**

The Fast Flash Programming Interface allows programming the device through either a serial JTAG interface or through a multiplexed fully-handshaked parallel port. It allows gang-programming with market-standard industrial programmers.

The FFPI supports read, page program, page erase, full erase, lock, unlock and protect commands.

The Fast Flash Programming Interface is enabled and the Fast Programming Mode is entered when the TST pin and the PA0 and PA1 pins are all tied high and PA2 tied to low.

- The Flash of the SAM7SE512 is organized in 2048 pages of 256 bytes (dual plane). It reads as 131,072 32-bit words.
- The Flash of the SAM7SE256 is organized in 1024 pages of 256 bytes (single plane). It reads as 65,536 32-bit words.
- The Flash of the SAM7SE32 is organized in 256 pages of 128 bytes (single plane). It reads as 32,768 32-bit words.
- The Flash of the SAM7SE512/256 contains a 256-byte write buffer, accessible through a 32-bit interface.
- The Flash of the SAM7SE32 contains a 128-byte write buffer, accessible through a 32-bit interface.

8.1.4 SAM-BA® Boot

The SAM-BA Boot is a default Boot Program which provides an easy way to program in-situ the on-chip Flash memory.

The SAM-BA Boot Assistant supports serial communication via the DBGU or the USB Device Port.

- Communication via the DBGU supports a wide range of crystals from 3 to 20 MHz via software auto-detection.
- Communication via the USB Device Port is limited to an 18.432 MHz crystal.

The SAM-BA Boot provides an interface with SAM-BA Graphic User Interface (GUI).

The SAM-BA Boot is in ROM and is mapped in Flash at address 0x0 when GPNVM bit 2 is set to 0.

8.2 External Memories

The external memories are accessed through the External Bus Interface.

Refer to the memory map in [Figure 8-1 on page 22](#).

9. System Controller

The System Controller manages all vital blocks of the microcontroller: interrupts, clocks, power, time, debug and reset.

The System Controller peripherals are all mapped to the highest 4 Kbytes of address space, between addresses 0xFFFF F000 and 0xFFFF FFFF.

[Figure 9-1 on page 29](#) shows the System Controller Block Diagram.

[Figure 8-1 on page 22](#) shows the mapping of the User Interface of the System Controller peripherals. Note that the Memory Controller configuration user interface is also mapped within this address space.

9.5 Debug Unit

- Comprises:
 - One two-pin UART
 - One Interface for the Debug Communication Channel (DCC) support
 - One set of Chip ID Registers
 - One Interface providing ICE Access Prevention
- Two-pin UART
 - USART-compatible User Interface
 - Programmable Baud Rate Generator
 - Parity, Framing and Overrun Error
 - Automatic Echo, Local Loopback and Remote Loopback Channel Modes
- Debug Communication Channel Support
 - Offers visibility of COMMRX and COMMTX signals from the ARM Processor
- Chip ID Registers
 - Identification of the device revision, sizes of the embedded memories, set of peripherals
 - Chip ID is 0x272A 0A40 (VERSION 0) for SAM7SE512
 - Chip ID is 0x272A 0940 (VERSION 0) for SAM7SE256
 - Chip ID is 0x2728 0340 (VERSION 0) for SAM7SE32

9.6 Periodic Interval Timer

- 20-bit programmable counter plus 12-bit interval counter

9.7 Watchdog Timer

- 12-bit key-protected Programmable Counter running on prescaled SLCK
- Provides reset or interrupt signals to the system
- Counter may be stopped while the processor is in debug state or in idle mode

9.8 Real-time Timer

- 32-bit free-running counter with alarm running on prescaled SLCK
- Programmable 16-bit prescaler for SLCK accuracy compensation

9.9 PIO Controllers

- Three PIO Controllers. PIO A and B each control 32 I/O lines and PIO C controls 24 I/O lines.
- Fully programmable through set/clear registers
- Multiplexing of two peripheral functions per I/O line
- For each I/O line (whether assigned to a peripheral or used as general-purpose I/O)
 - Input change interrupt
 - Half a clock period glitch filter
 - Multi-drive option enables driving in open drain
 - Programmable pull-up on each I/O line
 - Pin data status register, supplies visibility of the level on the pin at any time

- Synchronous output, provides Set and Clear of several I/O lines in a single write

9.10 Voltage Regulator Controller

The purpose of this controller is to select the Power Mode of the Voltage Regulator between Normal Mode (bit 0 is cleared) or Standby Mode (bit 0 is set).

10.4 PIO Controller A Multiplexing

Table 10-2. Multiplexing on PIO Controller A

PIO Controller A				Application Usage	
I/O Line	Peripheral A	Peripheral B	Comments	Function	Comments
PA0	PWM0	A0/NBS0	High-Drive		
PA1	PWM1	A1/NBS2	High-Drive		
PA2	PWM2	A2	High-Drive		
PA3	TWD	A3	High-Drive		
PA4	TWCK	A4			
PA5	RXD0	A5			
PA6	TXD0	A6			
PA7	RTS0	A7			
PA8	CTS0	A8			
PA9	DRXD	A9			
PA10	DTXD	A10			
PA11	NPCS0	A11			
PA12	MISO	A12			
PA13	MOSI	A13			
PA14	SPCK	A14			
PA15	TF	A15			
PA16	TK	A16/BA0			
PA17	TD	A17/BA1	AD0		
PA18	RD	NBS3/CFIOW	AD1		
PA19	RK	NCS4/CFCS0	AD2		
PA20	RF	NCS2/CFCS1	AD3		
PA21	RXD1	NCS6/CFCE2			
PA22	TXD1	NCS5/CFCE1			
PA23	SCK1	NWR1/NBS1/CFIOR			
PA24	RTS1	SDA10			
PA25	CTS1	SDCKE			
PA26	DCD1	NCS1/SDCS			
PA27	DTR1	SDWE			
PA28	DSR1	CAS			
PA29	RI1	RAS			
PA30	IRQ1	D30			
PA31	NPCS1	D31			

10.5 PIO Controller B Multiplexing

Table 10-3. Multiplexing on PIO Controller B

PIO Controller B				Application Usage	
I/O Line	Peripheral A	Peripheral B	Comments	Function	Comments
PB0	TIOA0	A0/NBS0			
PB1	TIOB0	A1/NBS2			
PB2	SCK0	A2			
PB3	NPCS3	A3			
PB4	TCLK0	A4			
PB5	NPCS3	A5			
PB6	PCK0	A6			
PB7	PWM3	A7			
PB8	ADTRG	A8			
PB9	NPCS1	A9			
PB10	NPCS2	A10			
PB11	PWM0	A11			
PB12	PWM1	A12			
PB13	PWM2	A13			
PB14	PWM3	A14			
PB15	TIOA1	A15			
PB16	TIOB1	A16/BA0			
PB17	PCK1	A17/BA1			
PB18	PCK2	D16			
PB19	FIQ	D17			
PB20	IRQ0	D18			
PB21	PCK1	D19			
PB22	NPCS3	D20			
PB23	PWM0	D21			
PB24	PWM1	D22			
PB25	PWM2	D23			
PB26	TIOA2	D24			
PB27	TIOB2	D25			
PB28	TCLK1	D26			
PB29	TCLK2	D27			
PB30	NPCS2	D28			
PB31	PCK2	D29			

- 8- to 16-bit programmable data length per chip select
- Programmable phase and polarity per chip select
- Programmable transfer delays per chip select, between consecutive transfers and between clock and data
- Programmable delay between consecutive transfers
- Selectable mode fault detection
- Maximum frequency at up to Master Clock

10.8 Two Wire Interface

- Master, Multi-Master and Slave Mode Operation
- Compatibility with standard two-wire serial memories
- One, two or three bytes for slave address
- Sequential read/write operations
- Bit Rate: Up to 400 Kbit/s
- General Call Supported in Slave Mode

10.9 USART

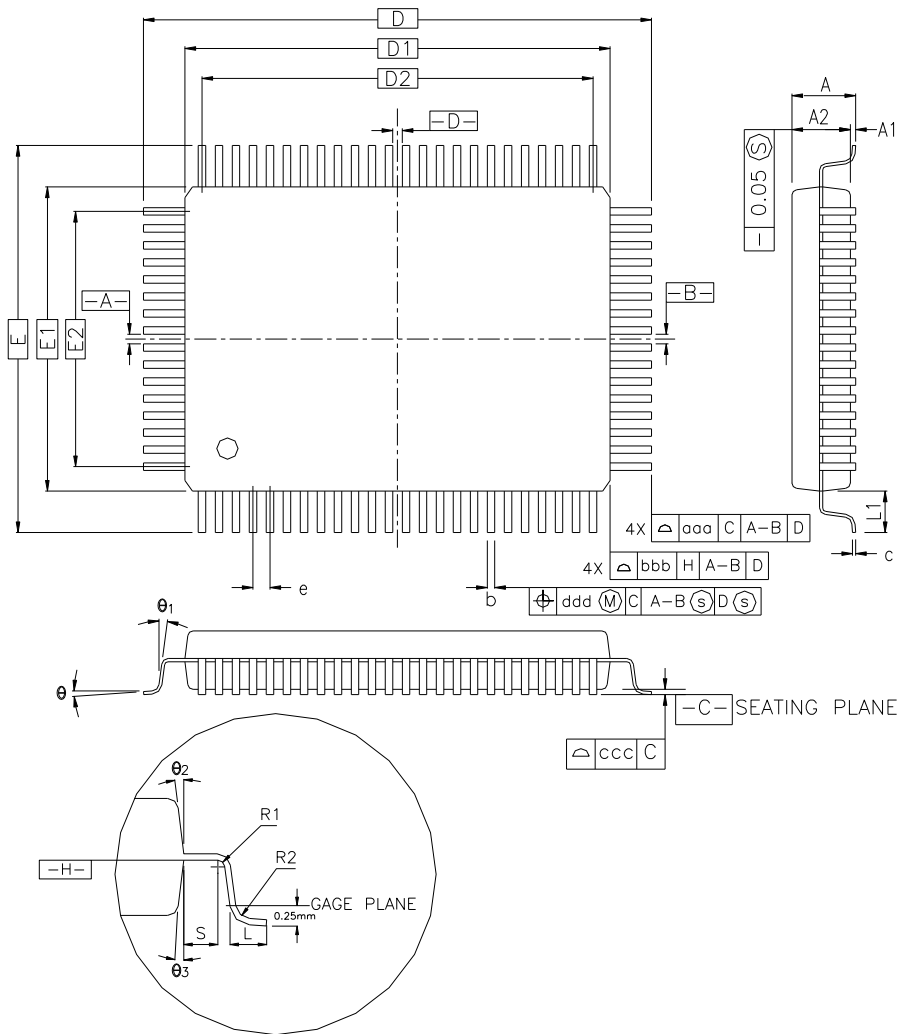
- Programmable Baud Rate Generator
- 5- to 9-bit full-duplex synchronous or asynchronous serial communications
 - 1, 1.5 or 2 stop bits in Asynchronous Mode
 - 1 or 2 stop bits in Synchronous Mode
 - Parity generation and error detection
 - Framing error detection, overrun error detection
 - MSB or LSB first
 - Optional break generation and detection
 - By 8 or by 16 over-sampling receiver frequency
 - Hardware handshaking RTS - CTS
 - Modem Signals Management DTR-DSR-DCD-RI on USART1
 - Receiver time-out and transmitter timeguard
 - Multi-drop Mode with address generation and detection
- RS485 with driver control signal
- ISO7816, T = 0 or T = 1 Protocols for interfacing with smart cards
 - NACK handling, error counter with repetition and iteration limit
- IrDA[®] modulation and demodulation
 - Communication at up to 115.2 Kbps
- Test Modes
 - Remote Loopback, Local Loopback, Automatic Echo

10.10 Serial Synchronous Controller

- Provides serial synchronous communication links used in audio and telecom applications
- Contains an independent receiver and transmitter and a common clock divider

11. Package Drawings

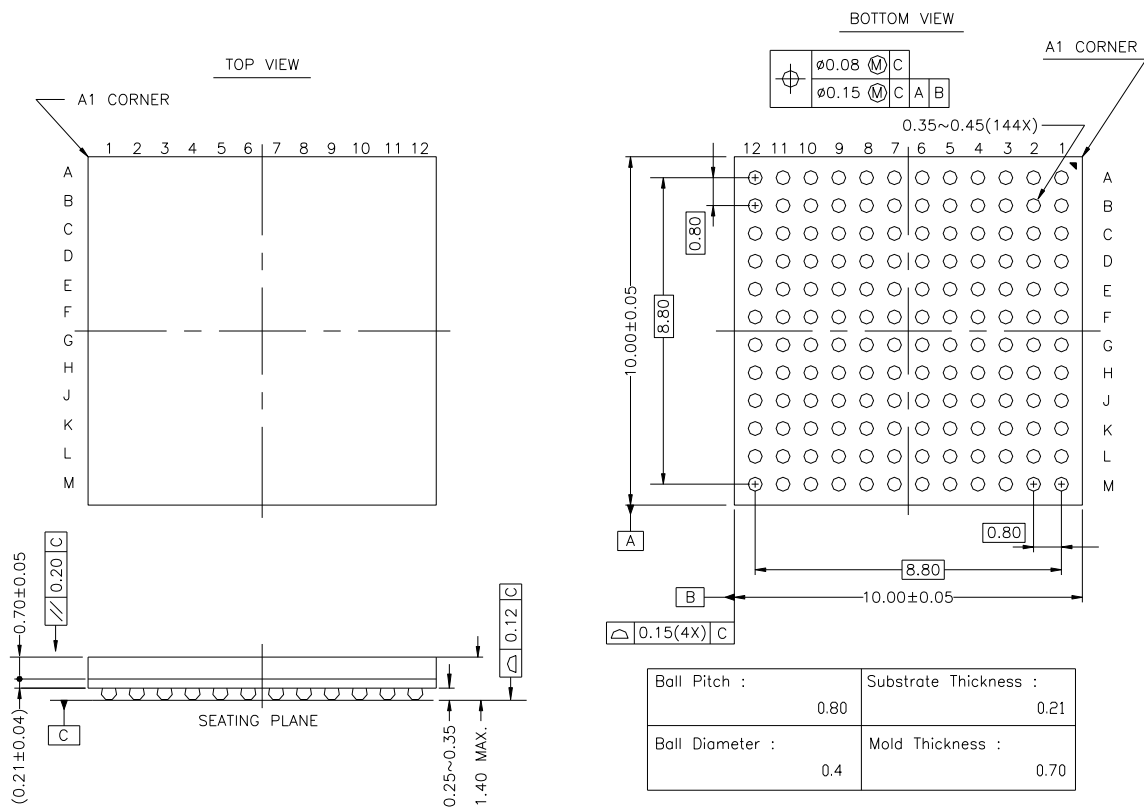
Figure 11-1. 128-lead LQFP Package Drawing



CONTROL DIMENSIONS ARE IN MILLIMETERS.

SYMBOL	MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	—	—	1.60	—	—	0.063
A1	0.05	—	0.15	0.002	—	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	22.00 BSC.			0.866 BSC.		
D1	20.00 BSC.			0.787 BSC.		
E	16.00 BSC.			0.630 BSC.		
E1	14.00 BSC.			0.551 BSC.		
R2	0.08	—	0.20	0.003	—	0.008
R1	0.08	—	—	0.003	—	—
θ	0°	3.5°	7°	0°	3.5°	7°
θ ₁	0°	—	—	0°	—	—
θ ₂	11°	12°	13°	11°	12°	13°
θ ₃	11°	12°	13°	11°	12°	13°
c	0.09	—	0.20	0.004	—	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L ₁	1.00 REF			0.039 REF		
S	0.20	—	—	0.008	—	—
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	18.50			0.728		
E2	12.50			0.492		
TOLERANCES OF FORM AND POSITION						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Figure 11-2. 144-ball LFBGA Package Drawing



All dimensions are in mm

12. Ordering Information

Table 12-1. Ordering Information

Ordering Code	MRL	Package	Package Type	Temperature Operating Range
AT91SAM7SE512B-AU	B	LQFP128	Green	Industrial (-40° C to 85° C)
AT91SAM7SE256B-AU	B	LQFP128	Green	Industrial (-40° C to 85° C)
AT91SAM7SE32B-AU	B	LQFP128	Green	Industrial (-40° C to 85° C)
AT91SAM7SE512B-CU	B	LFBGA144	Green	Industrial (-40° C to 85° C)
AT91SAM7SE256B-CU	B	LFBGA144	Green	Industrial (-40° C to 85° C)
AT91SAM7SE32B-CU	B	LFBGA144	Green	Industrial (-40° C to 85° C)
AT91SAM7SE512-AU	A	LQFP128	Green	Industrial (-40° C to 85° C)
AT91SAM7SE256-AU	A	LQFP128	Green	Industrial (-40° C to 85° C)
AT91SAM7SE32-AU	A	LQFP128	Green	Industrial (-40° C to 85° C)
AT91SAM7SE512-CU	A	LFBGA144	Green	Industrial (-40° C to 85° C)
AT91SAM7SE256-CU	A	LFBGA144	Green	Industrial (-40° C to 85° C)
AT91SAM7SE32-CU	A	LFBGA144	Green	Industrial (-40° C to 85° C)



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